

# RQ5L015SP

## Pch -60V -1.5A Small Signal MOSFET

V <sub>DSS</sub>	-60V
R <sub>DS(on)</sub> (Max.)	280mΩ
I <sub>D</sub>	±1.5A
P <sub>D</sub>	1.0W

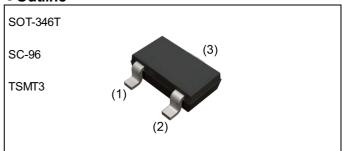
# ● Features

- 1) Low on resistance
- 2) High Power small mold Package (TSMT3)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen Free

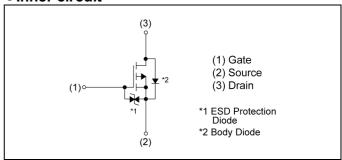
# Application

Switching

## Outline



## ●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TL
	Marking	FA

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	-60	V
Continuous drain current	I <sub>D</sub>	±1.5	Α
Pulsed drain current	I <sub>DP</sub> *1	±6	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Dower discipation	P <sub>D</sub> *2	1.0	W
Power dissipation	P <sub>D</sub> *3	0.7	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Doramator	Cumb of	Values			l lait
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres innetion, embient	R <sub>thJA</sub> *2	-	1	125	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *3	-	1	178	°C/W

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Cymah al	Symbol Conditions		Values			
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = -1mA$	-60	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = -1mA referenced to 25°C	-	-60	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -60V, V <sub>GS</sub> = 0V	-	-	-1	μА	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	1	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = -10V, I_{D} = -1mA$	-1.2	-	-3.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I <sub>D</sub> = -1mA referenced to 25°C	-	3.0	-	mV/°C	
		V <sub>GS</sub> = -10V, I <sub>D</sub> = -1.5A	-	200	280		
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	$V_{GS} = -4.5V, I_D = -1.5A$	-	240	340	mΩ	
		$V_{GS} = -4.0V, I_D = -1.5A$	-	255	360		
Gate resistance	$R_G$	f = 1MHz, open drain	-	12	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1.5A	1.8	-	-	S	

<sup>\*1</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*2</sup> Mounted on a ceramic boad (30×30×0.8mm)

<sup>\*3</sup> Mounted on a FR4 (25×25×0.8mm)

<sup>\*4</sup> Pulsed

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cymah al	Conditions	Values			Unit
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	500	-	_
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = -10V	-	70	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	30	-	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq -30V, V_{GS} = -10V$	-	8	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = -0.75A	-	10	-	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 25\Omega$	-	40	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	10	-	

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

	\ a	,				
Parameter	Cymbol	Conditions	Values			l leit
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Qg*4	V <sub>DD</sub> ≃ <b>-</b> 30V.	-	10	-	
Gate - Source charge	Q <sub>gs</sub> *4	$V_{DD} \approx -30V,$ $I_{D} = -1.5A,$ $V_{GS} = -10V$	-	1.5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	V <sub>GS</sub> = -10V	-	1.0	-	

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			l leit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	-0.8	Α
Pulse forward current	I <sub>SP</sub> *1	T <sub>a</sub> = 25°C	-	-	-6.0	Α
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1.5A	-	-	-1.2	V

Fig.1 Power Dissipation Derating Curve

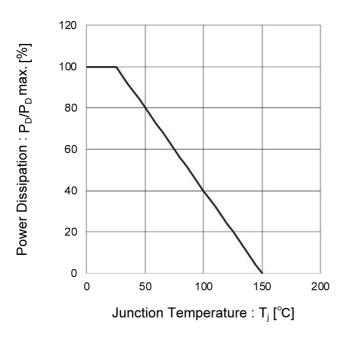
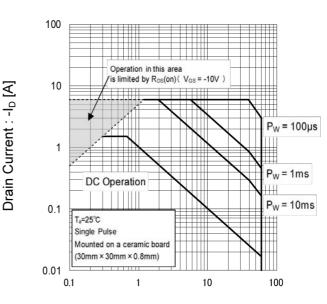


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

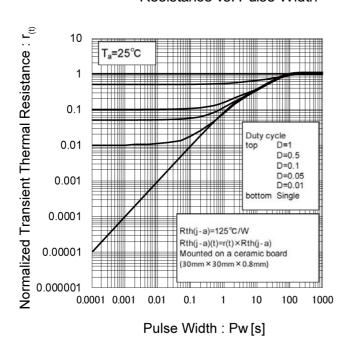
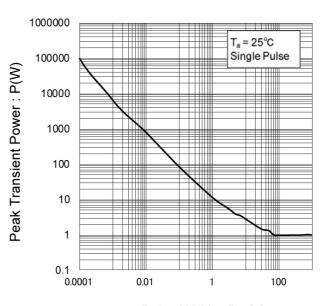


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width: Pw[s]

Fig.5 Typical Output Characteristics(I)

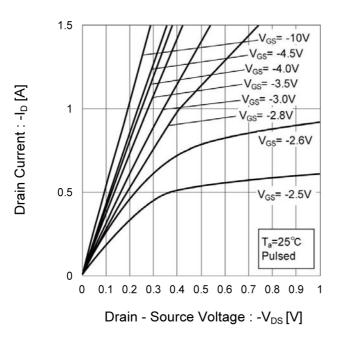
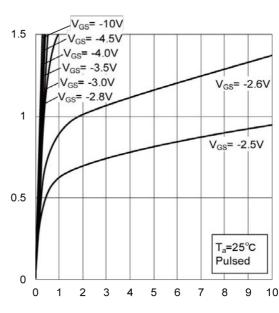


Fig.6 Typical Output Characteristics(II)



Drain Current : -I<sub>D</sub> [A]

Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs. Junction Temperature

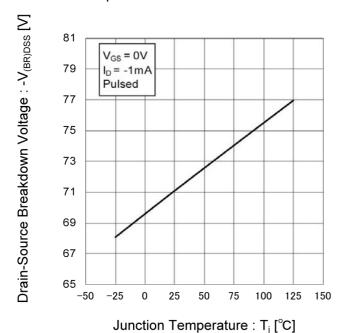


Fig.8 Typical Transfer Characteristics

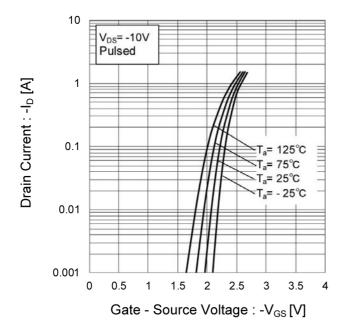


Fig.9 Gate Threshold Voltage vs. Junction Temperature

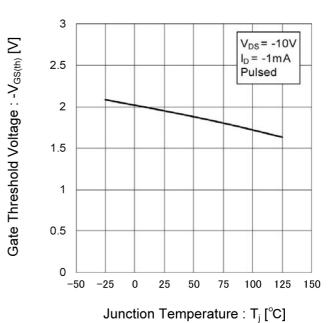


Fig.10 Forward Transfer Admittance vs. Drain Current

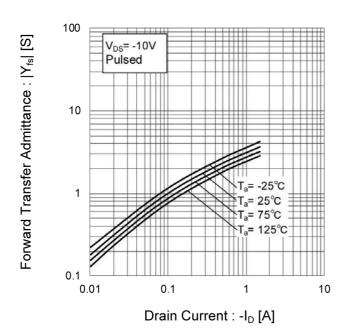


Fig.11 Drain Current Derating Curve

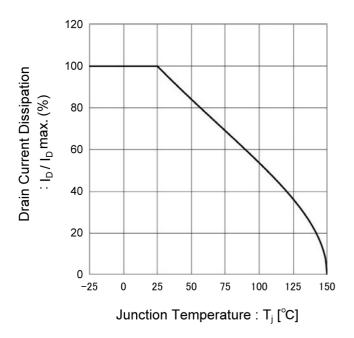


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

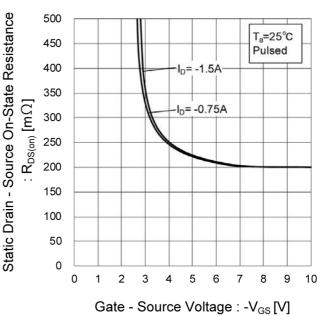


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

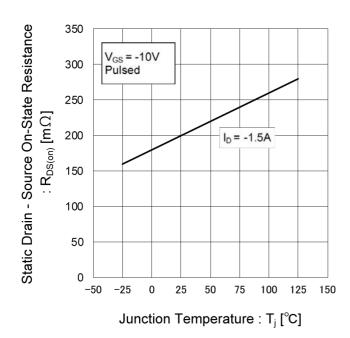


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

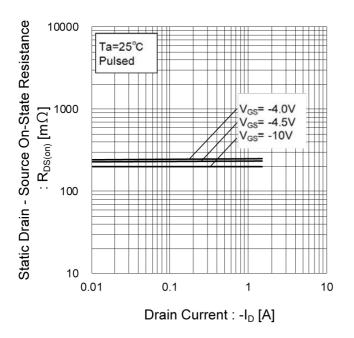


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

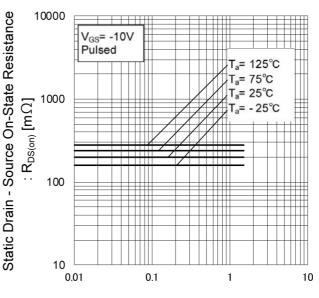


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

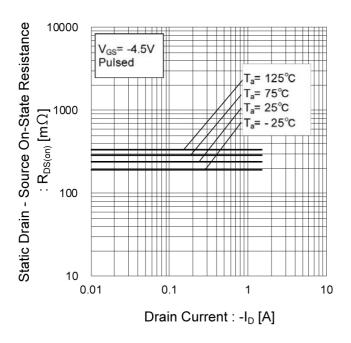


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

Drain Current: -ID [A]

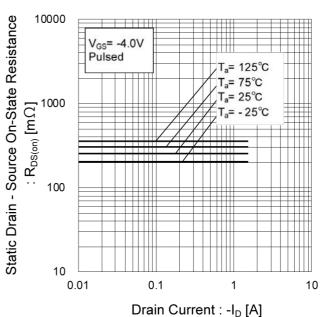


Fig.18 Typical Capacitance vs. Drain - Source Voltage

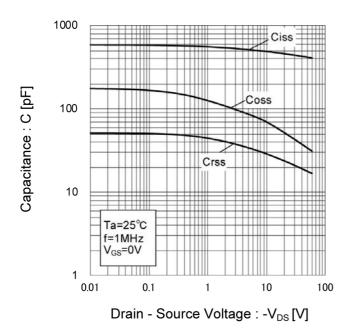


Fig.19 Switching Characteristics

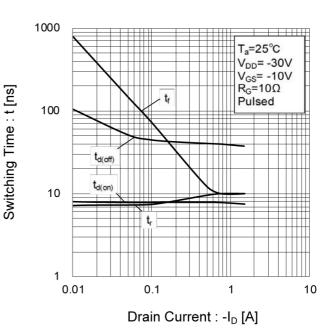


Fig.20 Dynamic Input Characteristics

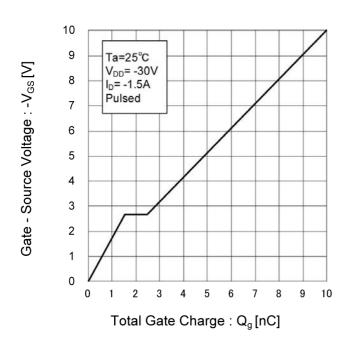
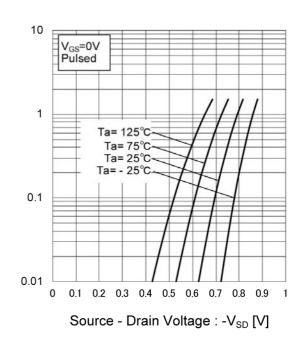


Fig.21 Source Current vs. Source Drain Voltage



Source Current : -I<sub>s</sub> [A]

### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

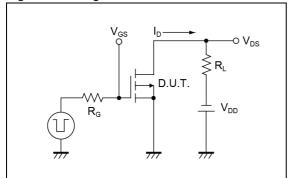


Fig.2-1 Gate Charge Measurement Circuit

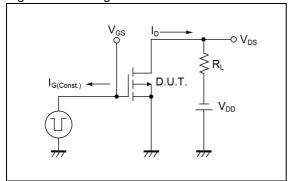


Fig.1-2 Switching Waveforms

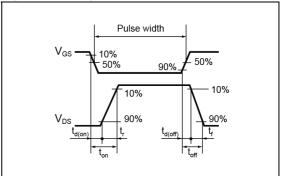
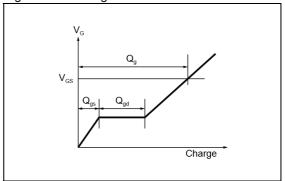


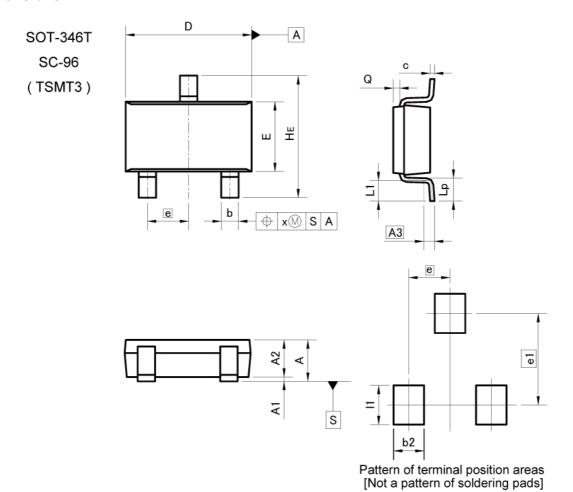
Fig.2-2 Gate Charge Waveform



### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

## Dimensions



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	=3	1.00	<del>-</del>	0.039
A1	0.00	0.10	0.000	0.004
A2	0.75	0.95	0.030	0.037
A3	0.	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.10	0.26	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.0	37
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.010
x	75%	0.20		0.008

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b2		0.70	<del>57</del> 0	0.028
e1	2.	2.10		083
11	=0.	0.90	<del>77</del> .%	0.035

Dimension in mm/inches



# **Notice**

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CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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**Rev.001** 

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